



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-02-03
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Emilio Castelli	<b>Representative Title</b>	APG MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA7569BLV	S848*UK79AA6	B	SH1A	2014-02-03
	Amount	UoM	Unit type	ST ECOPACK Grade
	7108.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMO	29.23x15.7x4.5	27	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	true
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	S848*UK79AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	29.940	mg	supplier	die	Silicon (Si)	7440-21-3		28.624	mg	956045	4027
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.188	mg	6279	26
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	6279	26
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.229	mg	7649	32
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.046	mg	1536	6
die (s)				supplier	passivation	Indium Tin oxide ( In2O3.SnO2 )	50926-11-9		0.441	mg	14729	62
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.016	mg	534	2
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.044	mg	1470	6
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.146	mg	4876	21
die (s)				supplier	polymer die coating	Polymer resist (Black resist)	Proprietary		0.018	mg	601	3
Leadframe	Copper & its alloys	5212.855	mg	supplier	alloy	Copper (Cu)	7440-50-8		5203.057	mg	998120	732000
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		2.397	mg	460	337
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		4.376	mg	839	616
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		3.025	mg	580	426
Die attach		16.395	mg	JIG Table A	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	15.985	mg	974992	2249
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.246	mg	15005	35
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.164	mg	10003	23
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		5.275	mg	1000000	742
encapsulation		1804.950	mg	supplier	mold compound	Amorphous Silica	7631-86-9		1534.207	mg	850000	215842
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		108.297	mg	60000	15236
encapsulation				supplier	mold compound	epoxy resin	na		72.198	mg	40000	10157
encapsulation				supplier	mold compound	Phenol resin	na		72.198	mg	40000	10157
encapsulation				supplier	mold compound	Carbon black	1333-86-4		12.635	mg	7000	1778
encapsulation				JIG table B	mold compound	Bismuth (Bi)	7440-69-9		5.415	mg	3000	762
connections coating	Solder	38.585	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		38.585	mg	1000000	5428